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AMENDMENT TO THE CLAIMS:

1. (Currently amended) A method of manufacturing circuit boards, the method comprising steps of:

laminating a metal foil on one face of a prepreg sheet;

placing a mold-releasing sheet on another face of the prepreg sheet;

heating and pressing a given place of the prepreg sheet and the metal foil via the mold-releasing sheet by a partial heat and press means, after the placing step;

removing the heat and pressure of the given place while the mold-releasing sheet is being placed on the prepreg sheet, after the heating and pressing the given place;

cooling the prepreg, after the removing;

peeling off the mold-releasing sheet, after the cooling; ~~after heating and pressing the given place, and~~

heating and pressing an entire face of the prepreg sheet and the metal foil to form a metal laminated board, after the peeling off step, and

forming a circuit pattern by selectively etching the metal foil of the metal laminated board to form a circuit board,

wherein, the heating and pressing the given place are performed at a temperature higher than a softening point of a resin impregnated into the prepreg sheet so that the resin is kept in stage-B status, while the temperature and pressure of the pressing are set so that the resin is not hardened, not welded to the mold-release sheet and not pushed out of the prepreg sheet at the given place.

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2. (Currently amended) A method of manufacturing circuit boards comprising steps of:

laminating a first metal foil on one face of a first prepreg sheet;
placing a mold-releasing sheet on another face of the prepreg sheet;
heating and pressing a first given place of the first prepreg sheet and the first metal foil via the mold-releasing sheet by a partial heat and press means;
removing the heat and pressure of the given place while the mold-releasing sheet is being placed on the first prepreg sheet;
cooling the first prepreg sheet;
peeling off the mold-releasing sheet after heating and pressing the first given place;
laminating a board having a circuit pattern on the another face of the first prepreg sheet, after the peeling off step;
heating and pressing a second given place of the first prepreg sheet and the board, after laminating the board;
laminating a second prepreg sheet on the board, after heating and pressing the second given place;
heating and pressing a third given place of the second prepreg sheet and the board, after laminating the second prepreg sheet;
laminating a second metal foil on the second prepreg sheet, after heating and pressing the third given place;
heating and pressing a fourth given place of the second metal foil and the second prepreg sheet; [[and]]

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heating and pressing an entire face of the first prepreg sheet, the first metal foil, the board, the second prepreg sheet, and the second metal foil to form a multilayer metal laminated board, after heating and pressing the fourth given place, and
forming a circuit pattern by selectively etching the metal foil of the multilayer metal laminated board to form a multilayer circuit board.

wherein the heating and pressing the first given place to fourth given place are performed at a temperature higher than a softening point of a resin impregnated into the first and the second prepreg sheet so that the resin is kept in stage-B status, while the temperature and pressure of the pressing are set so that the resin is not hardened, not welded to the mold-release sheet and not pushed out of the first and the second prepreg sheet at the first given place to fourth given place.

3. (Cancelled)

4. (Previously presented) The manufacturing method as defined in claim 2, wherein the board having a circuit pattern is a composite of thermosetting resin and one of woven fiber or non-woven fiber.

5-6. (Cancelled)

7. (Previously presented) The manufacturing method as defined in claim 1 or claim 2, wherein the peeling off of the mold-releasing sheet includes peeling off the sheet from one end of the sheet toward another end.

8-28. (Cancelled)